

# RFH30N12 RFH30N15

## N-Channel Enhancement-Mode Power Field-Effect Transistors

August 1991

### Features

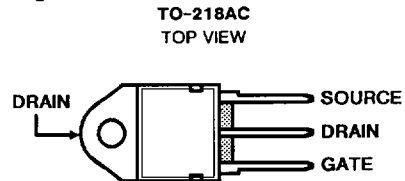
- 30A, 120V and 150V
- $r_{DS(on)} = 0.075\Omega$
- SOA is Power-Dissipation Limited
- Nanosecond Switching Speeds
- Linear Transfer Characteristics
- High Input Impedance
- Majority Carrier Device
- High-Carrier, Low-Inductance Package

### Description

The RFH30N12 and RFH30N15 are n-channel enhancement-mode silicon-gate power field-effect transistors designed for applications such as switching regulators, switching converters, motor drivers, relay drivers, and drivers for high-power bipolar switching transistors requiring high speed and low gate-drive power. These types can be operated directly from integrated circuits.

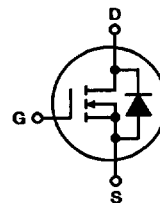
The RFH-types are supplied in the JEDEC TO-218AC plastic package.

### Package



### Terminal Diagram

#### N-CHANNEL ENHANCEMENT MODE


**4**
**N-CHANNEL  
POWER MOSFETS**

### Absolute Maximum Ratings ( $T_C = +25^\circ\text{C}$ ), Unless Otherwise Specified

	RFH30N12	RFH30N15	UNITS	
Drain-Source Voltage .....	$V_{DSS}$	120	150	V
Drain-Gate Voltage ( $R_{GS} = 1M\Omega$ ) .....	$V_{DGR}$	120	150	V
Continuous Drain Current .....	$I_D$	30	30	A
Pulsed Drain Current .....	$I_{DM}$	100	100	A
Gate-Source Voltage .....	$V_{GS}$	$\pm 20$	$\pm 20$	V
Maximum Power Dissipation				
$T_C = +25^\circ\text{C}$ .....	$P_D$	150	150	W
Linear Derating Factor .....		1.2	1.2	W/ $^\circ\text{C}$
Operating and Storage Temperature .....	$T_J, T_{STG}$	-55 to +150	-55 to +150	$^\circ\text{C}$

## Specifications RFH30N12, RFH30N15

**ELECTRICAL CHARACTERISTICS, at Case Temperature (T<sub>c</sub>) = 25° C unless otherwise specified.**

CHARACTERISTIC	SYMBOL	TEST CONDITIONS	LIMITS				UNITS
			RFH30N12		RFH30N15		
			Min.	Max.	Min.	Max.	
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	I <sub>D</sub> = 1 mA V <sub>GS</sub> = 0	120	—	150	—	V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>GS</sub> = V <sub>DS</sub> I <sub>D</sub> = 1 mA	2	4	2	4	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V	—	1	—	—	μA
		V <sub>DS</sub> = 120 V	—	—	—	1	
		T <sub>C</sub> = 125° C V <sub>DS</sub> = 100 V	—	50	—	—	
		V <sub>DS</sub> = 120 V	—	—	—	50	
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ± 20 V V <sub>DS</sub> = 0	—	100	—	100	nA
On-State Gate Voltage	V <sub>GS(on)</sub> <sup>a</sup>	V <sub>DS</sub> = 5 V I <sub>D</sub> = 15 A	—	8	—	8	V
		V <sub>DS</sub> = 10 V I <sub>D</sub> = 30 A	—	10	—	10	
Drain-Source On Voltage	V <sub>DS(on)</sub> <sup>a</sup>	I <sub>D</sub> = 15 A V <sub>GS</sub> = 10 V	—	1.125	—	1.125	V
		I <sub>D</sub> = 30 A V <sub>GS</sub> = 10 V	—	2.65	—	2.65	
Static Drain-Source On Resistance	r <sub>DS(on)</sub> <sup>a</sup>	I <sub>D</sub> = 15 A V <sub>GS</sub> = 10 V	—	0.075	—	0.075	Ω
Forward Transconductance	g <sub>fs</sub> <sup>a</sup>	V <sub>DS</sub> = 10 V I <sub>D</sub> = 15 A	10	—	10	—	mho
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 25 V	—	3000	—	3000	pF
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V	—	1200	—	1200	
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1 MHz	—	500	—	500	
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DS</sub> = 75 V	75(typ)	115	75(typ)	115	ns
Rise Time	t <sub>r</sub>	I <sub>D</sub> = 15 A	420(typ)	630	420(typ)	630	
Turn-Off Delay Time	t <sub>d(off)</sub>	R <sub>θen</sub> = R <sub>θs</sub> = 50Ω	300(typ)	450	300(typ)	450	
Fall Time	t <sub>f</sub>	V <sub>GS</sub> = 10 V	250(typ)	375	250(typ)	375	
Thermal Resistance Junction-to-Case	R <sub>θJC</sub>	RFH30N12, RFH30N15 Series	—	0.83	—	0.83	

<sup>a</sup>Pulsed: Pulse duration = 300 μs max., duty cycle = 2%.

### SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

CHARACTERISTIC	SYMBOL	TEST CONDITIONS	LIMITS				UNITS
			RFH30N12		RFH30N15		
			Min.	Max.	Min.	Max.	
Diode Forward Voltage	V <sub>SD</sub> *	I <sub>SD</sub> = 15A	—	1.4	—	1.4	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 4A, d <sub>IF</sub> /d <sub>t</sub> = 100 A/μs	200 (typ.)		200 (typ.)		ns

\* Pulse Test: Width ≤ 300 μs, Duty cycle ≤ 2%.

# RFH30N12, RFH30N15

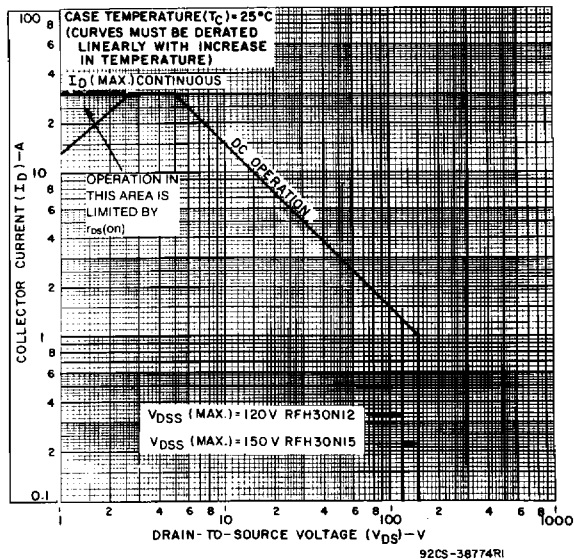


Fig. 1 - Maximum safe operating areas for all types.

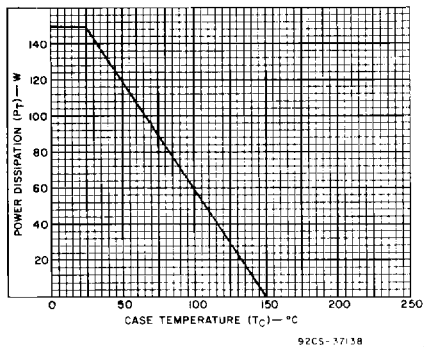


Fig. 2 - Power vs. temperature derating curve for all types.

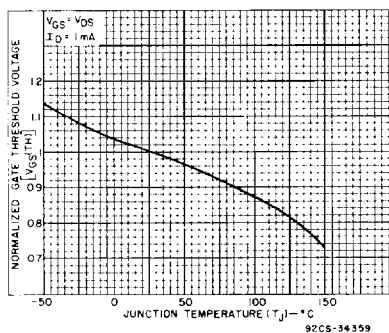


Fig. 3 - Typical normalized gate threshold voltage as a function of junction temperature for all types.

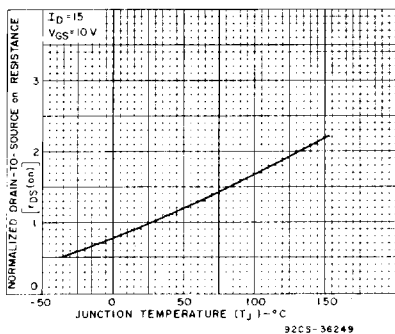


Fig. 4 - Normalized drain-to-source on resistance to junction temperature for all types.

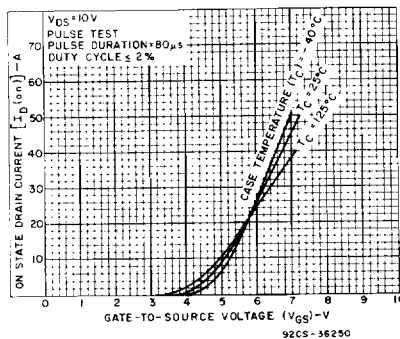


Fig. 5 - Typical transfer characteristics for all types.

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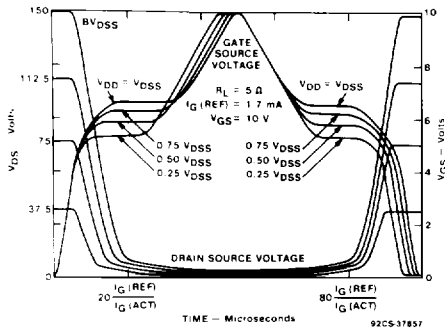


Fig. 6 - Normalized switching waveforms for constant gate-current. Refer to Harris application notes AN-7254 and AN-7260

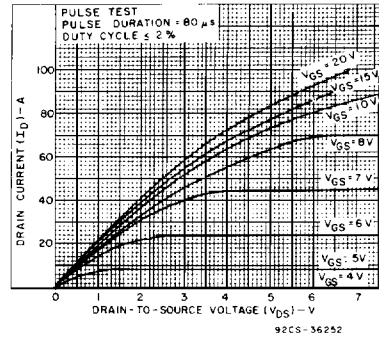


Fig. 7 - Typical saturation characteristics for all types.

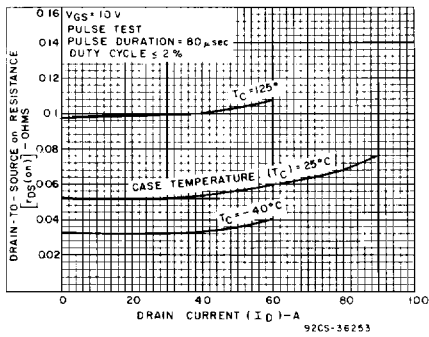


Fig. 8 - Typical drain-to-source on resistance as a function of drain current for all types.

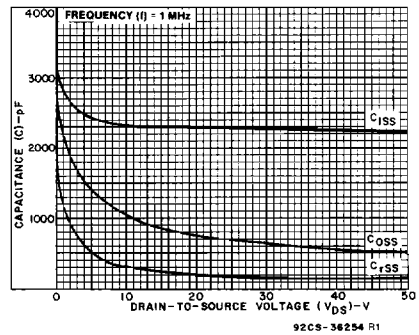


Fig. 9 - Capacitance as a function of drain-to-source voltage for all types.

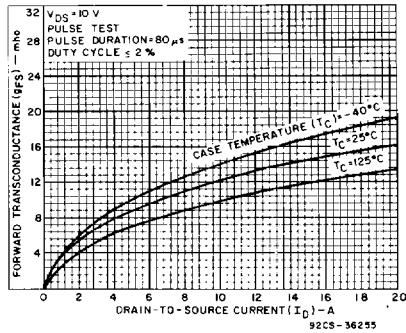


Fig. 10 - Typical forward transconductance as a function of drain current for all types.

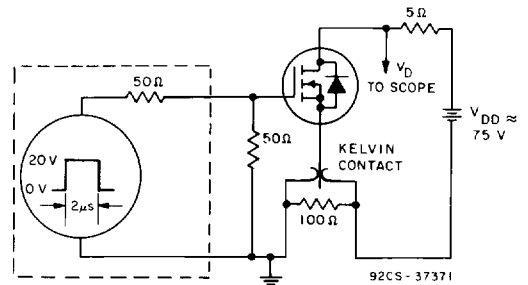


Fig. 11 - Switching Time Test Circuit.